Title (en)

Form-in-place EMI gaskets

Title (de)

In Situ gebildete elektromagnetisch abschirmende Dichtungen

Title (fr)

Joints de blindage électromagnétique formés sur place

Publication

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Application

EP 00113095 A 19960119

Priority

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- US 37585395 A 19950120
- US 37741295 A 19950124

Abstract (en)

A form-in-place, electrically-conductive gasket is disclosed as an EMI shielding gasket for use between mating housing components of electronic equipment. The gasket is formed of a fluent polymeric material including electrically-conductive particles disposed therein. A method and apparatus for forming the gasket involves extruding the electrically-conductive particle-filled fluent polymeric material from a system including several canisters (A, B, C) for containing various premixed components and a mixing chamber (78). Fluent polymeric material is fed from the canisters (A, B, C) to a chamber (141) in the extruder. Pressure is applied to the fluent polymeric material by a pressure supply system which includes a source of positive pressure (121) and negative pressure (125) and a control module (126) for selectively supplying positive and negative pressure to the extrusion chamber (141) to form a bead of electrically-conductive, fluent polymeric material on a substrate (115) which then is cured to form an EMI gasket. <IMAGE>

IPC 1-7

H05K 9/00

IPC 8 full level

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WO 9622672 A1 19960725; AU 4759196 A 19960807; CA 2210485 A1 19960725; CA 2210485 C 20100720; DE 69612277 D1 20010503; DE 69612277 T2 20010809; DE 69637903 D1 20090528; DK 0804868 T3 20010430; DK 1041869 T3 20090713; EP 0804868 A1 19971105; EP 0804868 B1 20010328; EP 1041869 A2 20001004; EP 1041869 A3 20001018; EP 1041869 B1 20090415; ES 2155929 T3 20010601; ES 2323745 T3 20090724; FI 119351 B 20081015; FI 973019 A0 19970716; FI 973019 A 19970905; JP 3971798 B2 20070905; JP H11500368 A 19990112; NO 973225 D0 19970710; NO 973225 L 19970922

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